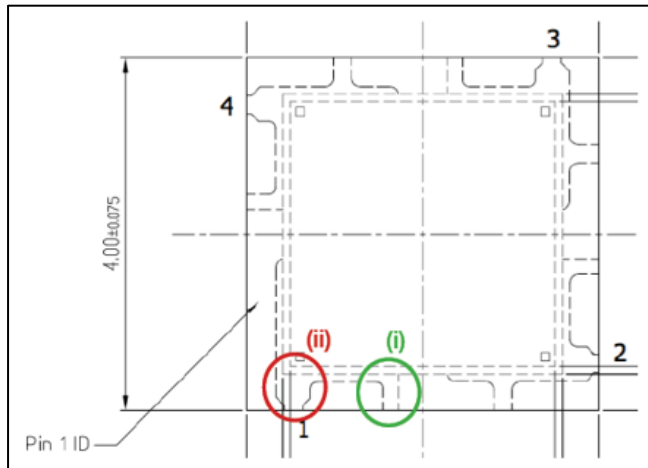
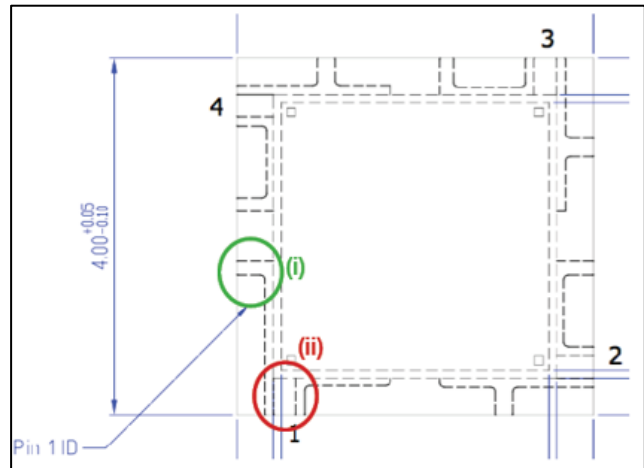




<b>Title of Change:</b>	Change of assembly and test site, lead frame design and mold compound for MicroFC-30020 and MicroFC-30050	
<b>Proposed First Ship date:</b>	19 Aug 2021 or earlier if approved by customer	
<b>Contact Information:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Deborah.Herbert@onsemi.com">Deborah.Herbert@onsemi.com</a>	
<b>PCN Samples Contact:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:PCN.samples@onsemi.com">PCN.samples@onsemi.com</a> . Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Ricky.Garcia@onsemi.com">Ricky.Garcia@onsemi.com</a>	
<b>Type of Notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a>	
<b>Marking of Parts/ Traceability of Change:</b>	No OPN change. No marking, but visible leadframe change. Traceability will be via Assembly Lot date code.	
<b>Change Category:</b>	Assembly Change	
<b>Change Sub-Category(s):</b>	Manufacturing Site Transfer, Material Change	
<b>Sites Affected:</b>		
<b>ON Semiconductor Sites</b>	<b>External Foundry/Subcon Sites</b>	
None	Site A Site B	
<b>Description and Purpose:</b>		
	<b>Before Change Description (Site A)</b>	<b>After Change Description (Site B)</b>
Leadframe	Refer to image and description below	Refer to image and description below
Mold compound	NITTO NT-332H Clear CPD	NITTO NT-8524H Clear CPD
<b>Leadframe change description:</b> No base material change as a result of this change.		

**BEFORE****AFTER**

(i) The half-etch tab on pin 1 is relocated - the half etch tabs do not contact the base of the package as there is package material underneath so there is no change to the package footprint and the recommended solder footprint has not changed.

(ii) The pull in etch of the solder pads 1 - 4 at the edge of the package have been changed to a flat edge. There is no change to the recommended solder footprint.

The full POD documents can be accessed as follows:

Before:

<https://www.onsemi.com/pub/collateral/512ah.pdf>

After:

<https://www.onsemi.com/pub/collateral/512af.pdf>

There is no product marking change as a result of this change.

**Sample Availability:**

Samples will be available at the end of May 2021

**Qualification Plan:**

**QV DEVICE NAME :** MicroFC-30035-SMT

**RMS :** N/A

**PACKAGE :** CWDFN-4 4x4

Parts are qualified by similarity to MicroFC-30035-SMT product which is already complete. Qualification of MicroFC-30035-SMT included MSL3 preconditioning, 3 x solder reflow, UHAST (110°C, 85%RH), temperature cycling (-40°C – 85°C), HTS (504HRS, 125°C).

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
MICROFC-30050-SMT-TR1	NA
MICROFC-30050-SMT-TR	NA
MICROFC-30020-SMT-TR1	NA
MICROFC-30020-SMT-TR	NA



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**Appendix A: Changed Products**

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**PCN#: FPCN23931Y**  
**Issue Date: May 12, 2021**

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Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
MICROFC-30050-SMT-TR1		NA	NA	
MICROFC-30020-SMT-TR1		NA	NA	